

SOT1787-1

CFM4F, ceramic, flange mount flat package; 4 terminals; 13.72 mm pitch, 10.16 mm x 41.15 mm x 4.575 mm body

15 November 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	CFM4F
Package style descriptive code	CFM (ceramic flange mount)
Package body material type	C (ceramic)
Mounting method type	F (flange mount)
Issue date	25-10-2019
Manufacturer package code	98ASB16977C

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	41.02	41.15	41.28	mm
package width	10.03	10.16	10.29	mm
package height	4.32	4.575	4.83	mm
nominal pitch	-	13.72	-	mm
actual quantity of termination	-	4	-	



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2 Package outline

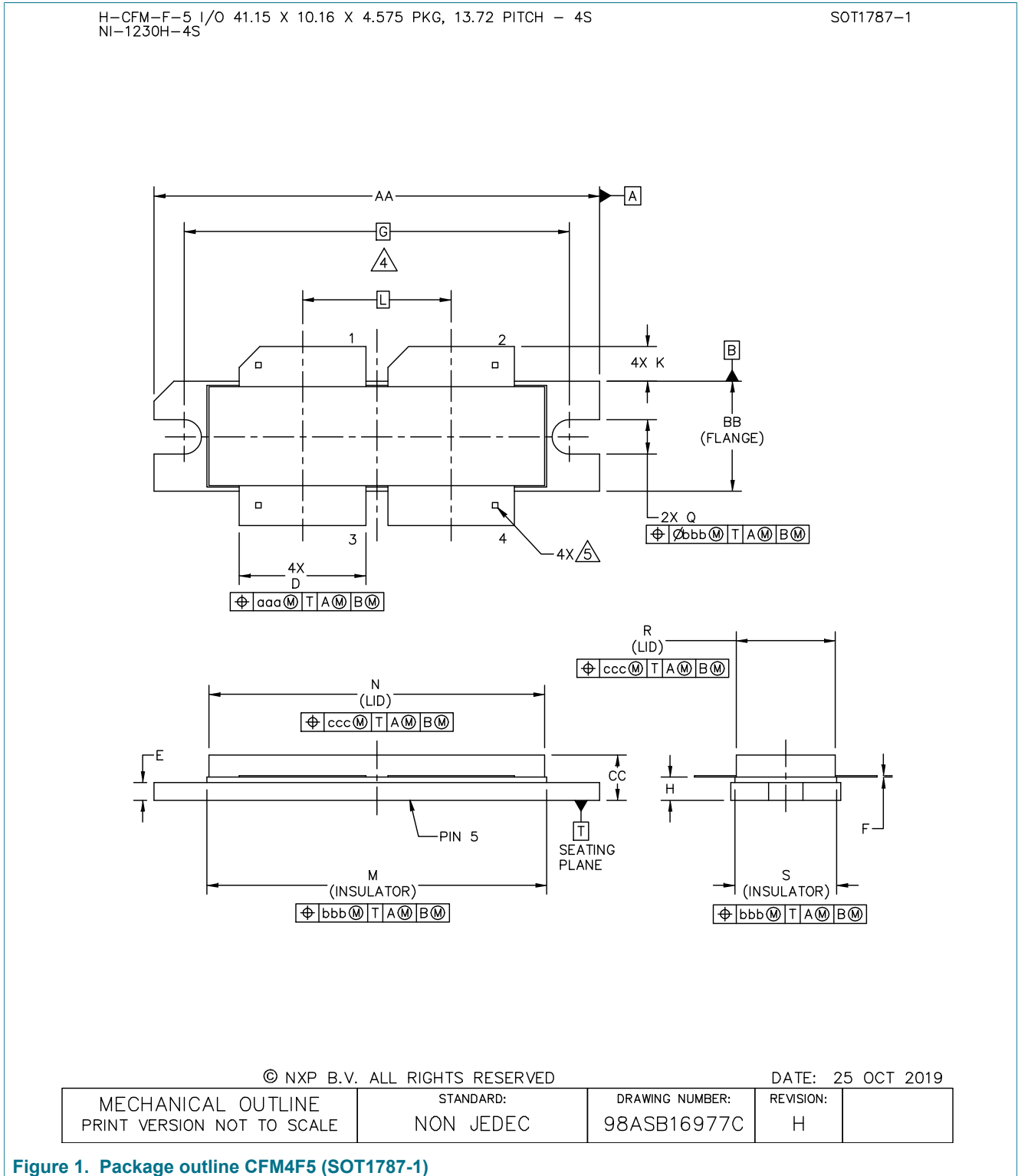


Figure 1. Package outline CFM4F5 (SOT1787-1)

CFM4F, ceramic, flange mount flat package; 4 terminals; 13.72 mm pitch, 10.16 mm x 41.15 mm x 4.575 mm body

3 Soldering

H-CFM-F-5 I/O 41.15 X 10.16 X 4.575 PKG, 13.72 PITCH - 4S
 NI-1230H-4S

SOT1787-1

NOTES:

1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH
3. DIMENSION H IS MEASURED .030 INCH (0.762 MM) AWAY FROM THE FLANGE TO CLEAR THE EPOXY FLOW OUT REGION PARALLEL TO DATUM B.

4. RECOMMENDED BOLT CENTER DIMENSION OF 1.52 INCH (38.61 MM) BASED ON M3 SCREW.

5. FIDUCIALS ARE OPTIONAL ON PINS 3 & 4.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	1.615	1.625	41.02	41.28	N	1.218	1.242	30.94	31.55
BB	.395	.405	10.03	10.29	Q	.120	.130	3.05	3.30
CC	.170	.190	4.32	4.83	R	.355	.365	9.02	9.27
D	.455	.465	11.56	11.81	S	.365	.375	9.27	9.53
E	.062	.066	1.57	1.68					
F	.004	.007	0.10	0.18					
G	1.400 BSC		35.56 BSC		aaa	.013		0.33	
H	.082	.090	2.08	2.29	bbb	.010		0.25	
K	.117	.137	2.97	3.48	ccc	.020		0.51	
L	.540 BSC		13.72 BSC						
M	1.219	1.241	30.96	31.52					

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DATE: 25 OCT 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASB16977C	REVISION: H	
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Figure 2. Package outline note CFM4F5 (SOT1787-1)

4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering3
4 Legal information4